

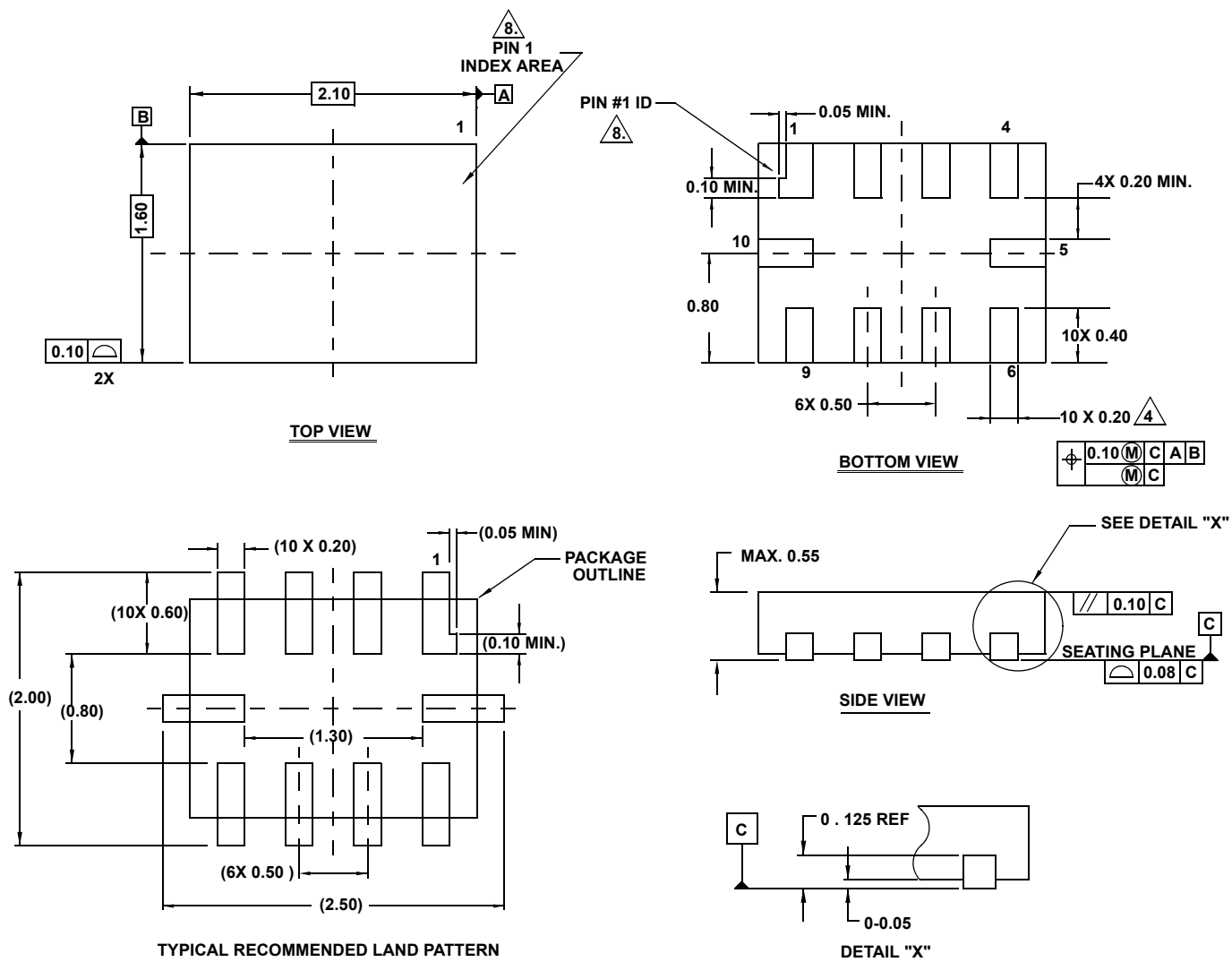
Plastic Packages for Integrated Circuits

Package Outline Drawing

L10.2.1X1.6A

10 LEAD ULTRA THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE

REV 5, 3/10



NOTES:

1. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
2. All Dimensions are in millimeters. Angles are in degrees. Dimensions in () for Reference Only.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Lead width dimension applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
5. Maximum package warpage is 0.05mm.
6. Maximum allowable burrs is 0.076mm in all directions.
7. Same as JEDEC MO-255UABD except:
No lead-pull-back, MIN. Package thickness = 0.45 not 0.50mm
Lead Length dim. = 0.45mm max. not 0.42mm.
8. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.